

3.3 VOLT ZERO DELAY CLOCK MULTIPLIER

IDT2308B

Description

The IDT2308B is a high-speed phase-lock loop (PLL) clock multiplier. It is designed to address high-speed clock distribution and multiplication applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 133 MHz.

The IDT2308B has two banks of four outputs each that are controlled via two select addresses. By proper selection of input addresses, both banks can be put in tri-state mode. In test mode, the PLL is turned off, and the input clock directly drives the outputs for system testing purposes. In the absence of an input clock, the IDT2308B enters power down, and the outputs are tri-stated. In this mode, the device will draw less than 25 μ A.

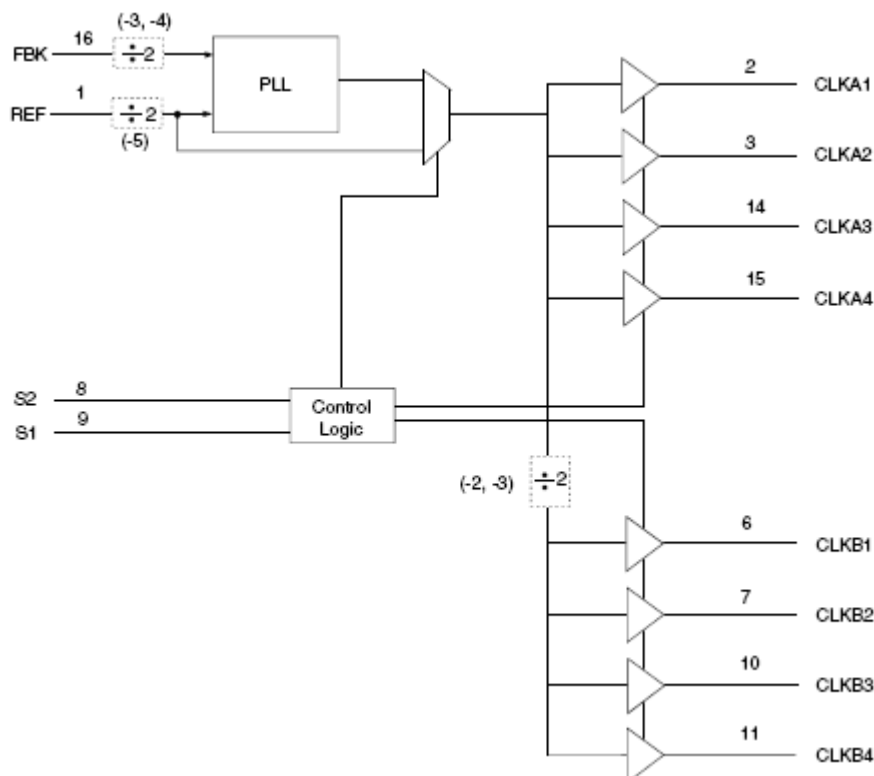
The IDT2308B is available in six unique configurations for both prescaling and multiplication of the Input REF Clock. (see Available Options table.)

The PLL is closed externally to provide more flexibility by allowing the user to control the delay between the input clock and the outputs.

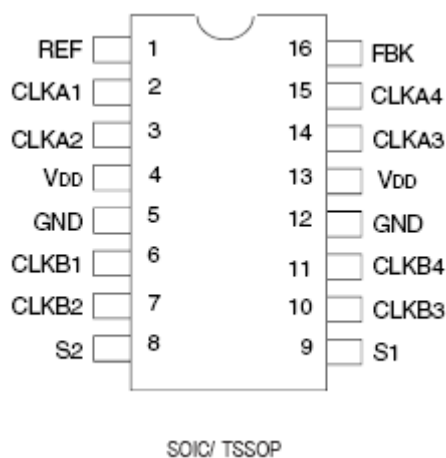
Features

- Phase-Lock Loop Clock Distribution for Applications ranging from 10 MHz to 133 MHz operating frequency
- Distributes one clock input to two banks of four outputs
- Separate output enable for each output bank
- External feedback (FBK) pin is used to synchronize the outputs to the clock input
- Output Skew <200 ps
- Low jitter <200 ps cycle-to-cycle
- 1x, 2x, 4x output options (see Available Options table)
- No external RC network required
- Operates at 3.3 V V_{DD}
- Available in 16-pin SOIC and TSSOP packages
- Available in Commercial and Industrial temperature ranges

Block Diagram



Pin Assignment



Applications

- SDRAM
- Telecom
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs

Function Table¹ Select Input Decoding

S2	S1	CLKA	CLKB	Output Source	PLL Shut Down
L	L	Tri-state	Tri-state	PLL	Y
L	H	Driven	Tri-state	PLL	N
H	L	Driven	Driven	REF	Y
H	H	Driven	Driven	PLL	N

Note 1: H = HIGH voltage level; L = LOW voltage level

Pin Descriptions

Pin Number	Pin Name	Pin Description
1	REF ¹	Input Reference Clock, 5 Volt Tolerant Input
2	CLKA1 ²	Clock Output for Bank A
3	CLKA2 ²	Clock Output for Bank A
4	VDD	3.3 V Supply
5	GND	Ground
6	CLKB1 ²	Clock Output for Bank B
7	CLKB2 ²	Clock Output for Bank B
8	S2 ³	Select Input, Bit 2
9	S1 ³	Select Input, Bit 1
10	CLKB3 ²	Clock Output for Bank B
11	CLKB4 ²	Clock Output for Bank B
12	GND	Ground
13	VDD	3.3 V Supply
14	CLKA3 ²	Clock Output for Bank A
15	CLKA4 ²	Clock Output for Bank A
16	FBK	PLL Feedback Input

Notes:

1. Weak pull-down.
2. Weak pull-down on all outputs.
3. Weak pull-up on these inputs.

Available Options for IDT2308B

Device	Feedback From	Bank A Frequency	Bank B Frequency
IDT2308B-1	Bank A or Bank B	Reference	Reference
IDT2308B-1H	Bank A or Bank B	Reference	Reference
IDT2308B-2	Bank A	Reference	Reference/2
IDT2308B-2	Bank B	2 x Reference	Reference
IDT2308B-2H	Bank A	Reference	Reference/2
IDT2308B-2H	Bank B	2 x Reference	Reference
IDT2308B-3	Bank A	2 x Reference	Reference or $\overline{\text{Reference}}$ ¹
IDT2308B-3	Bank B	4 x Reference	2 x Reference
IDT2308B-4	Bank A or Bank B	2 x Reference	2 x Reference
IDT2308B-5H	Bank A or Bank B	Reference/2	Reference/2

Note 1: Output phase is indeterminant (0° or 180° from input clock).

Absolute Maximum Ratings¹

Symbol	Rating	Max.	Unit
V_{DD}	Supply Voltage Range	-0.5 V to +4.6	V
V_I^2	Input Voltage Range (REF)	-0.5 V to +5.5	V
V_I	Input Voltage Range (except REF)	-0.5 to $V_{DD} + 0.5$	V
$I_{IK} (V_I < 0)$	Input Clamp Current	-50	mA
$I_{OK} (V_O < 0 \text{ or } V_O > V_{DD})$	Terminal Voltage with Respect to GND (inputs V_{IH} 2.5, V_{IL} 2.5)	±50	mA
$I_O (V_O = 0 \text{ to } V_{DD})$	Continuous Output Current	±50	mA
V_{DD} or GND	Continuous Current	±100	mA
$T_A = 55^\circ\text{C}$ (in still air only) ³	Maximum Power Dissipation	0.7	W
T_{STG}	Storage Temperature Range	-65 to +150	°C
Operating Temperature	Commercial range	0 to +70	°C
Operating Temperature	Industrial range	-40 to +85	°C

Notes:

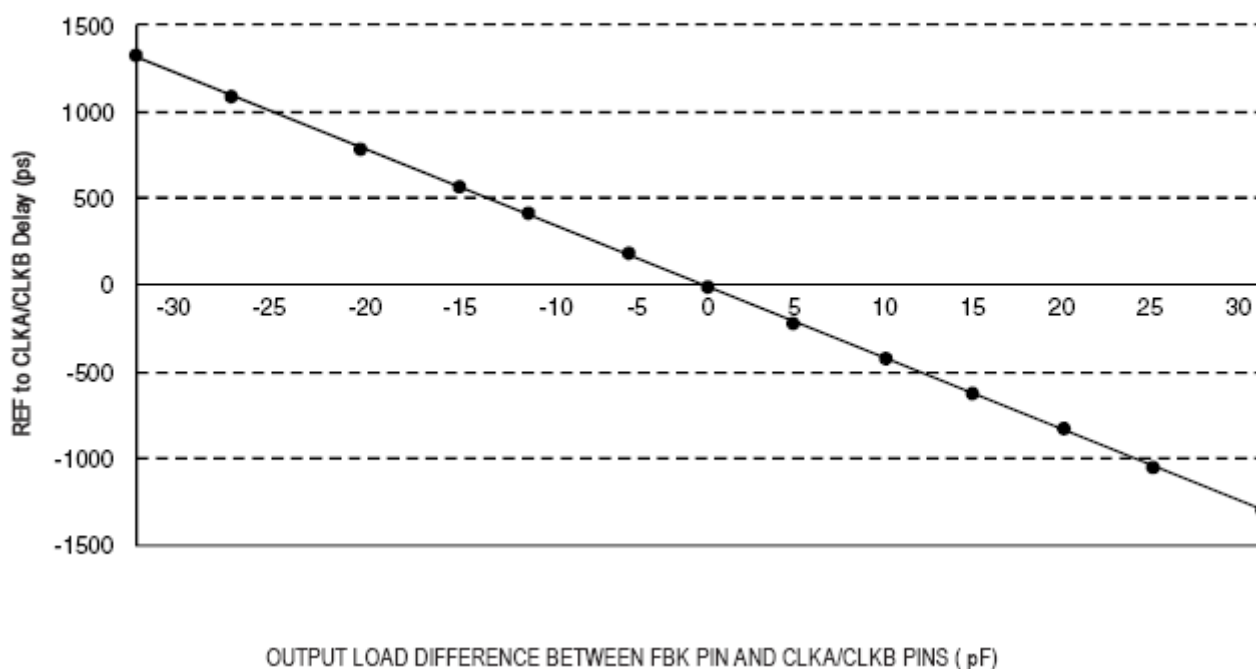
- Stresses above the ratings listed below can cause permanent damage to the IDT2308B. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

Zero Delay and Skew Control

To close the feedback loop of the IDT2308B, the FBK pin can be driven from any of the eight available output pins. The output driving the FBK pin will be driving a total load of 7 pF plus any additional load that it drives. The relative loading of this output (with respect to the remaining outputs) can adjust the input-output delay.

For applications requiring zero input-output delay, all outputs including the one providing feedback should be equally loaded. If input-output delay adjustments are required, use the Output Load Difference Chart to calculate loading differences between the feedback output and remaining outputs. Ensure the outputs are loaded equally, for zero output-output skew.

REF TO CLKA/CLKB DELAY vs. OUTPUT LOAD DIFFERENCE BETWEEN FBK PIN AND CLKA/CLKB PINS



Operating Conditions–Commercial

Symbol	Parameter	Conditions	Min.	Max.	Units
V_{DD}	Supply Voltage		3	3.6	V
T_A	Operating Temperature (Ambient Temperature)		0	70	°C
C_L	Load Capacitance below 100 MHz		–	30	pF
	Load Capacitance from 100 MHz to 133 MHz		–	15	pF
C_{IN}	Input Capacitance ¹		–	7	pF

Note 1: Applies to both REF and FBK.

DC Electrical Characteristics–Commercial

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input High Voltage Level	V_{IH}		2			V
Input Low Voltage Level	V_{IL}				0.8	V
Input Low Current	I_{IL}	$V_{IN} = 0V$			50	μA
Input High Current	I_{IH}	$V_{IN} = V_{DD}$			100	μA
Output High Voltage	V_{OH}	$I_{OH} = -8\text{ mA (-1, -2, -3, -4)}$ $I_{OH} = -12\text{ mA (-1H, -2H, -5H)}$	2.4			V
Output Low Voltage	V_{OL}	$I_{OL} = 8\text{ mA (-1, -2, -3, -4)}$ $I_{OL} = 12\text{ mA (-1H, -2H, -5H)}$			0.4	V
Power Down Current	I_{DD_PD}	REF = 0MHz (S2 = S1 = H)			12	μA
Supply Current	I_{DD}	Unloaded Outputs Select Inputs at V_{DD} or GND	100 MHz CLKA (-1, -2, -3, -4)		45	mA
			100 MHz CLKA (-1H, -2H, -5H)		70	
			66 MHz CLKA (-1, -2, -3, -4)		32	
			66 MHz CLKA (-1H, -2H, -5H)		50	
			33 MHz CLKA (-1, -2, -3, -4)		18	
			33 MHz CLKA (-1H, -2H, -5H)		30	

Switching Characteristics—Commercial

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Frequency	t_1	30 pF Load, all devices	10		100	MHz
Output Frequency	t_1	20 pF Load, -1H, -2H, -5H Devices ¹	10		133.3	MHz
Output Frequency	t_1	15pF Load, -1, -2, -3, -4 devices	10		133.3	MHz
Duty Cycle = $t_2 \div t_1$ (-1, -2, -3, -4, -1H, -2H, -5H)		Measured at 1.4V, FOUT = 66.66MHz, 30pF Load	40	50	60	%
Duty Cycle = $t_2 \div t_1$ (-1, -2, -3, -4, -1H, -2H, -5H)		Measured at 1.4V, FOUT = 50MHz, 15pF Load	45	50	55	%
Rise Time (-1, -2, -3, -4)	t_3	Measured between 0.8V and 2V, 30pF Load			2.2	ns
Rise Time (-1, -2, -3, -4)	t_3	Measured between 0.8V and 2V, 15pF Load			1.5	ns
Rise Time (-1H, -2H, -5H)	t_3	Measured between 0.8V and 2V, 30pF Load			1.5	ns
Fall Time (-1, -2, -3, -4)	t_4	Measured between 0.8V and 2V, 30pF Load			2.2	ns
Fall Time (-1, -2, -3, -4)	t_4	Measured between 0.8V and 2V, 15pF Load			1.5	ns
Fall Time (-1H, -5H)	t_4	Measured between 0.8V and 2V, 30pF Load			1.25	ns
Output to Output Skew on same Bank (-1, -2, -3, -4)	t_5	All outputs equally loaded			200	ps
Output to Output Skew (-1H, -2H, -5H)		All outputs equally loaded			200	ps
Output Bank A to Output Bank B (-1, -4, -2H, -5H)		All outputs equally loaded			200	ps
Output Bank A to Output Bank B Skew (-2, -3)		All outputs equally loaded			400	ps
Delay, REF Rising Edge to FBK Rising Edge	t_6	Measured at VDD/2			±250	ps
Device to Device Skew	t_7	Measured at VDD/2 on the FBK pins of devices			700	ps
Output Slew Rate	t_8	Measured between 0.8V and 2V on -1H, -2H, -5H device using Test Circuit 2	1			V/ns
Cycle to Cycle Jitter (-1, -1H, -4, -5H)	t_J	Measured at 66.67 MHz, loaded outputs, 15pF Load			200	ps
		Measured at 66.67 MHz, loaded outputs, 30pF Load			200	
		Measured at 133.3 MHz, loaded outputs, 15pF Load			100	
Cycle to Cycle Jitter (-2, -2H, -3)	t_J	Measured at 66.67 MHz, loaded outputs, 30pF Load			400	ps
		Measured at 66.67 MHz, loaded outputs, 15pF Load			400	
PLL Lock Time	t_{LOCK}	Stable Power Supply, valid clocks presented on REF and FBK pins			1	ms

Note 1: IDT2308B-5H has maximum input frequency of 133.33 MHz and maximum output of 66.67 MHz.

Operating Conditions—Industrial

Symbol	Parameter	Conditions	Min.	Max.	Units
V_{DD}	Supply Voltage		3	3.6	V
T_A	Operating Temperature (Ambient Temperature)		-40	+85	°C
C_L	Load Capacitance below 100 MHz		–	30	pF
	Load Capacitance from 100 MHz to 133 MHz		–	15	pF
C_{IN}	Input Capacitance ¹		–	7	pF

Note 1: Applies to both REF and FBK.

DC Electrical Characteristics—Industrial

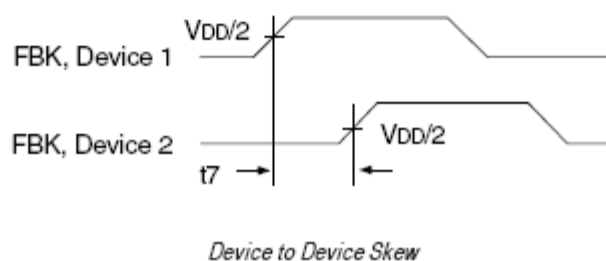
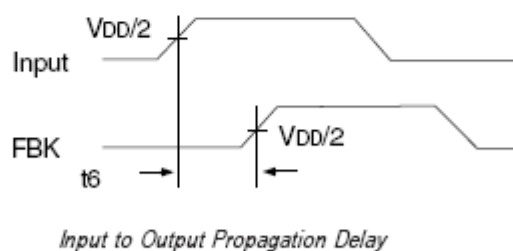
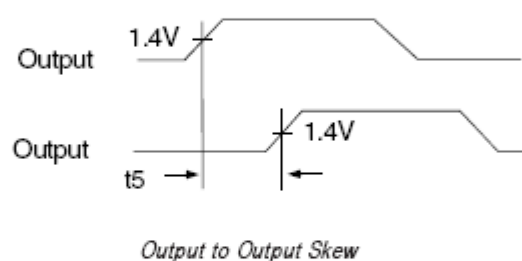
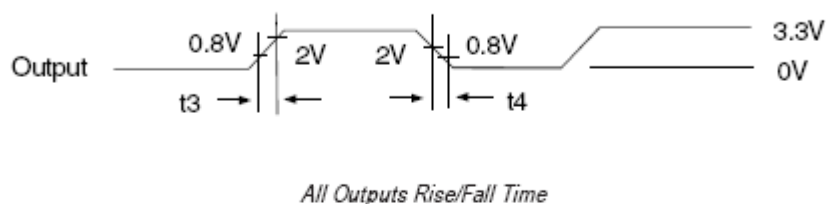
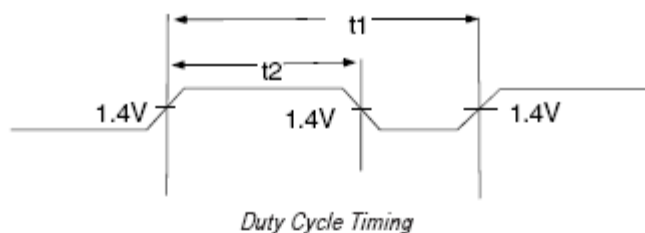
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input High Voltage Level	V_{IH}		2			V
Input Low Voltage Level	V_{IL}				0.8	V
Input Low Current	I_{IL}	$V_{IN} = 0V$			50	μA
Input High Current	I_{IH}	$V_{IN} = V_{DD}$			100	μA
Output High Voltage	V_{OH}	$I_{OH} = -8\text{ mA (-1, -2, -3, -4)}$ $I_{OH} = -12\text{ mA (-1H, -2H, -5H)}$	2.4			V
Output Low Voltage	V_{OL}	$I_{OL} = 8\text{ mA (-1, -2, -3, -4)}$ $I_{OL} = 12\text{ mA (-1H, -2H, -5H)}$			0.4	V
Power Down Current	I_{DD_PD}	REF = 0MHz (S2 = S1 = H)			25	μA
Supply Current	I_{DD}	Unloaded Outputs Select Inputs at V_{DD} or GND	100 MHz CLKA (-1, -2, -3, -4)		45	mA
			100 MHz CLKA (-1H, -2H, -5H)		70	
			66 MHz CLKA (-1, -2, -3, -4)		32	
			66 MHz CLKA (-1H, -2H, -5H)		50	
			33 MHz CLKA (-1, -2, -3, -4)		18	
			33 MHz CLKA (-1H, -2H, -5H)		30	

Switching Characteristics—Industrial

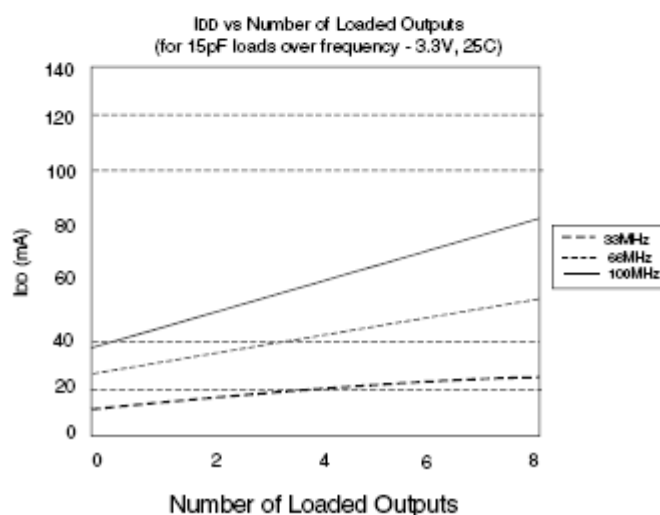
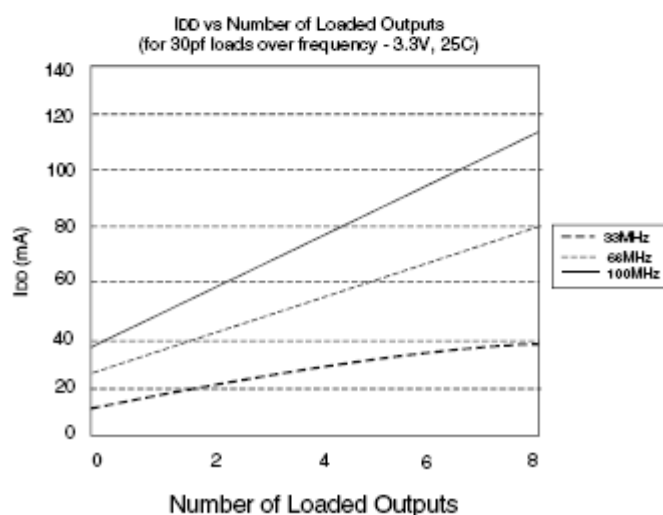
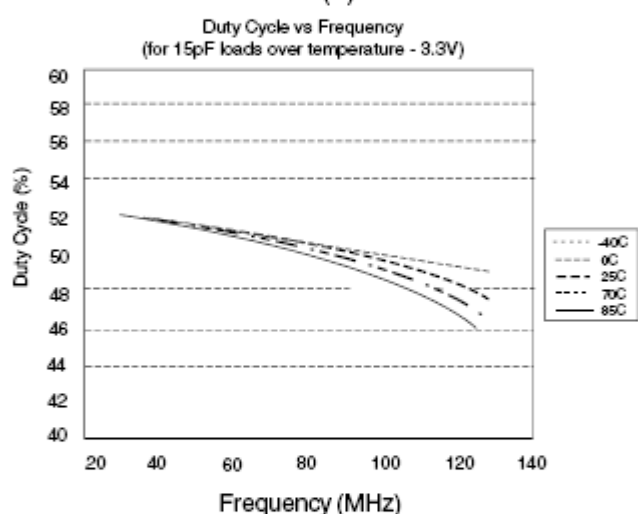
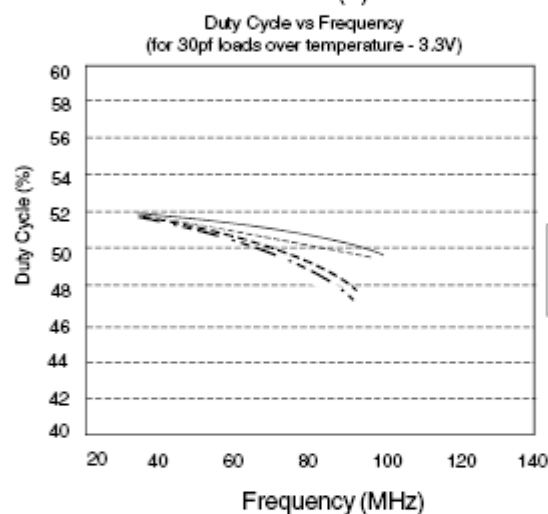
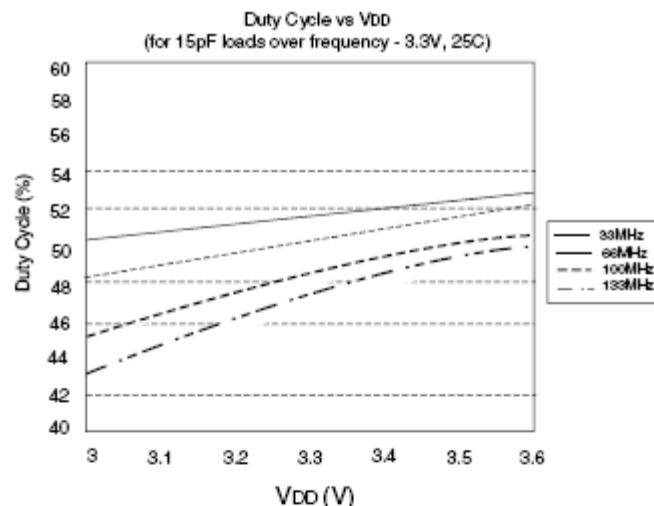
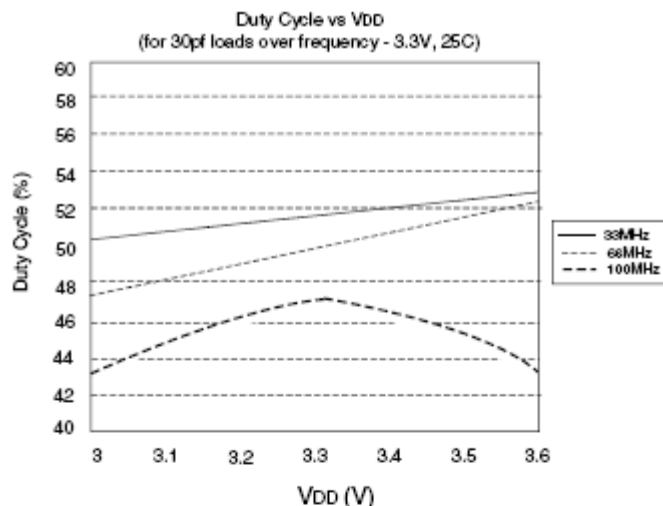
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Output Frequency	t_1	30 pF Load, all devices	10		100	MHz
Output Frequency	t_1	20 pF Load, -1H, -2H, -5H Devices ¹	10		133.3	MHz
Output Frequency	t_1	15pF Load, -1, -2, -3, -4 devices	10		133.3	MHz
Duty Cycle = $t_2 \div t_1$ (-1, -2, -3, -4, -1H, -2H, -5H)		Measured at 1.4V, FOUT = 66.66 MHz, 30 pF Load	40	50	60	%
Duty Cycle = $t_2 \div t_1$ (-1, -2, -3, -4, -1H, -2H, -5H)		Measured at 1.4V, FOUT = 50 MHz, 15 pF Load	45	50	55	%
Rise Time (-1, -2, -3, -4)	t_3	Measured between 0.8V and 2V, 30pF Load			2.2	ns
Rise Time (-1, -2, -3, -4)	t_3	Measured between 0.8V and 2V, 15pF Load			1.5	ns
Rise Time (-1H, -2H, -5H)	t_3	Measured between 0.8V and 2V, 30pF Load			1.5	ns
Fall Time (-1, -2, -3, -4)	t_4	Measured between 0.8V and 2V, 30pF Load			2.2	ns
Fall Time (-1, -2, -3, -4)	t_4	Measured between 0.8V and 2V, 15pF Load			1.5	ns
Fall Time (-1H, -5H)	t_4	Measured between 0.8V and 2V, 30pF Load			1.25	ns
Output to Output Skew on same Bank (-1, -2, -3, -4)	t_5	All outputs equally loaded			200	ps
Output to Output Skew (-1H, -2H, -5H)		All outputs equally loaded			200	ps
Output Bank A to Output Bank B (-1, -4, -2H, -5H)		All outputs equally loaded			200	ps
Output Bank A to Output Bank B Skew (-2, -3)		All outputs equally loaded			400	ps
Delay, REF Rising Edge to FBK Rising Edge	t_6	Measured at VDD/2			±250	ps
Device to Device Skew	t_7	Measured at VDD/2 on the FBK pins of devices			700	ps
Output Slew Rate	t_8	Measured between 0.8V and 2V on -1H, -2H, -5H device using Test Circuit 2	1			V/ns
Cycle to Cycle Jitter (-1, -1H, -4, -5H)	t_J	Measured at 66.67 MHz, loaded outputs, 15pF Load			200	ps
		Measured at 66.67 MHz, loaded outputs, 30pF Load			200	
		Measured at 133.3 MHz, loaded outputs, 15pF Load			100	
Cycle to Cycle Jitter (-2, -2H, -3)	t_J	Measured at 66.67 MHz, loaded outputs, 30pF Load			400	ps
		Measured at 66.67 MHz, loaded outputs, 15pF Load			400	
PLL Lock Time	t_{LOCK}	Stable Power Supply, valid clocks presented on REF and FBK pins			1	ms

Note 1: IDT2308B-5H has maximum input frequency of 133.33 MHz and maximum output of 66.67 MHz.

Switching Waveforms



Typical Duty Cycle¹ and I_{DD} Trends² for IDT2308B-1, 2, 3, and 4

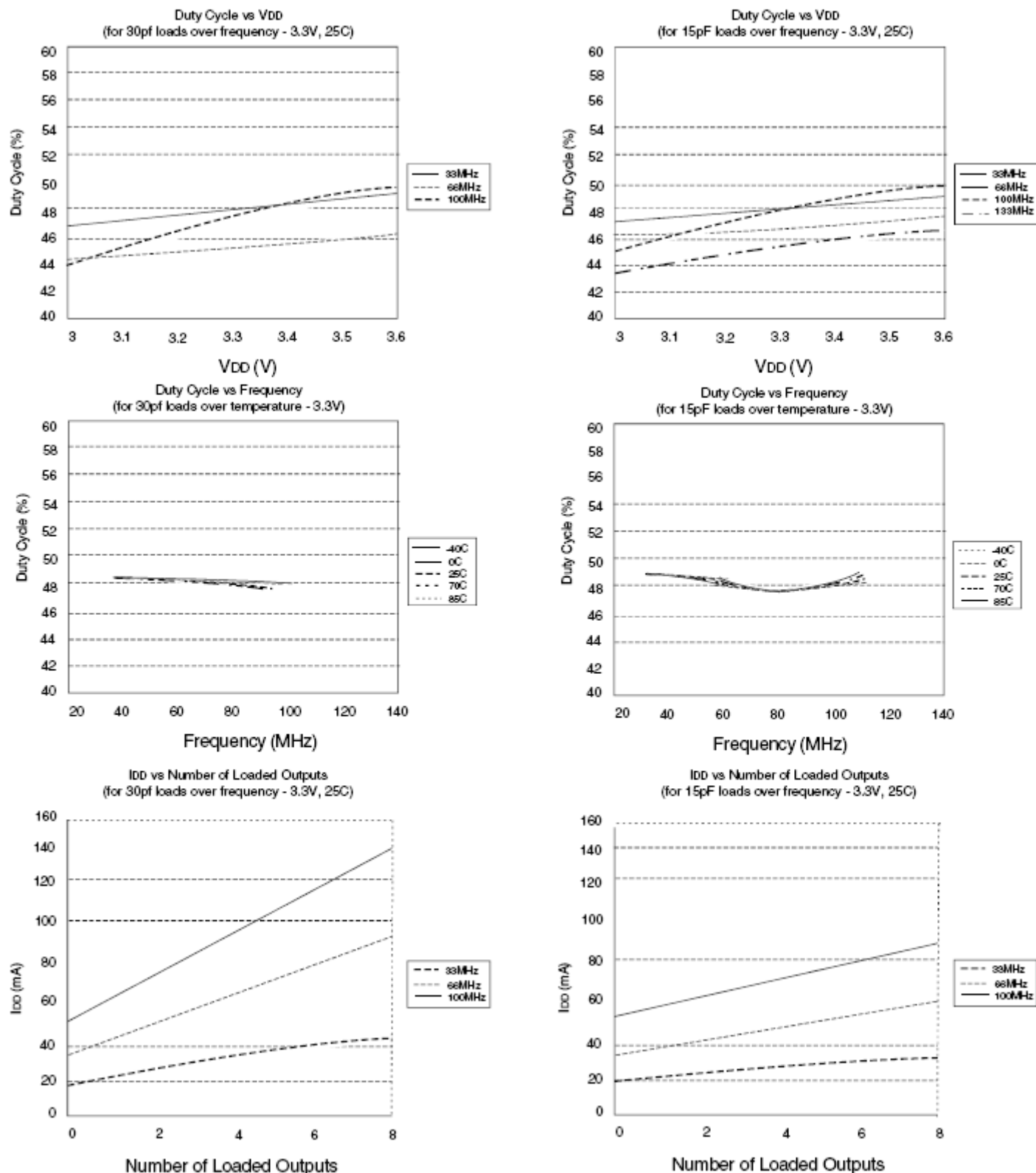


NOTES:

1. Duty Cycle is taken from typical chip measured at 1.4V.

2. I_{DD} data is calculated from $I_{DD} = I_{CORE} + nCVf$, where I_{CORE} is the Unloaded Current (n = Number of Outputs; C = Capacitance Load per Output (F); V = Voltage Supply(V); f = Frequency (Hz).

Typical Duty Cycle¹ and I_{DD} Trends² for IDT2308B-1H, 2H, and 5H

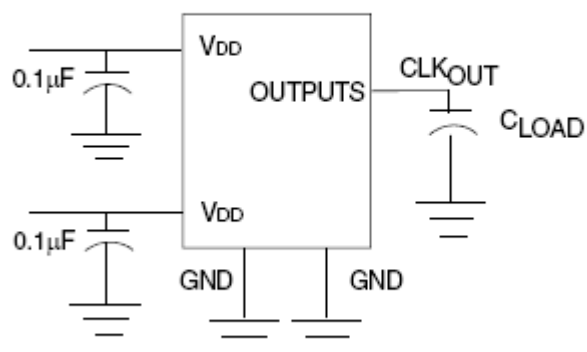


NOTES:

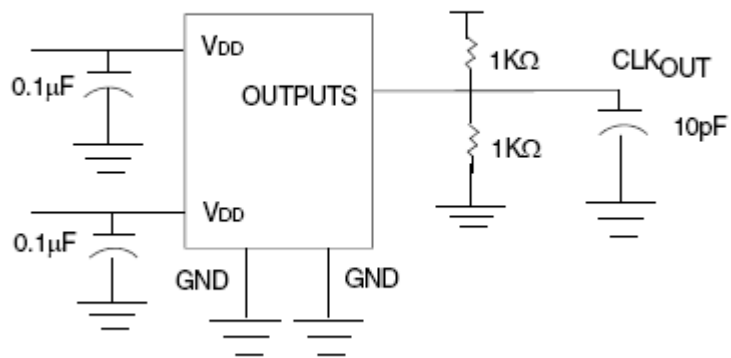
- Duty Cycle is taken from typical chip measured at 1.4V.
- I_{DD} data is calculated from $I_{DD} = I_{CORE} + nCVf$, where I_{CORE} is the Unloaded Current (n = Number of Outputs; C = Capacitance Load per Output (F); V = Voltage Supply(V); f = Frequency (Hz).

Test Circuits

TEST CIRCUIT 1

Test Circuit for all Parameters Except t_8

TEST CIRCUIT 2

Test Circuit for t_8 , Output Slew Rate On -1H, -2H, and -5H Device

Thermal Characteristics 16TSSOP

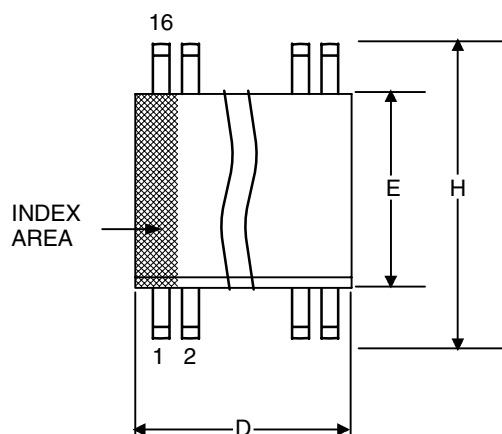
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		78		°C/W
	θ_{JA}	1 m/s air flow		70		°C/W
	θ_{JA}	3 m/s air flow		68		°C/W
Thermal Resistance Junction to Case	θ_{JC}			37		°C/W

Thermal Characteristics 16SOIC

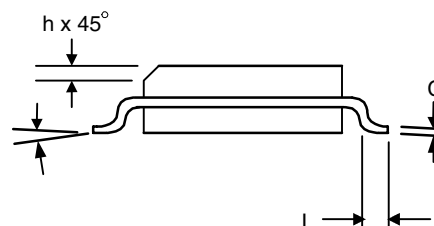
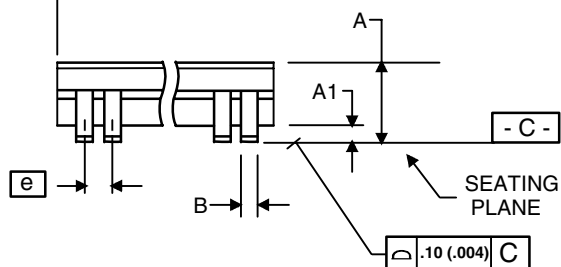
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		120		°C/W
	θ_{JA}	1 m/s air flow		115		°C/W
	θ_{JA}	3 m/s air flow		105		°C/W
Thermal Resistance Junction to Case	θ_{JC}			58		°C/W

Package Outline and Package Dimensions (16-pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95

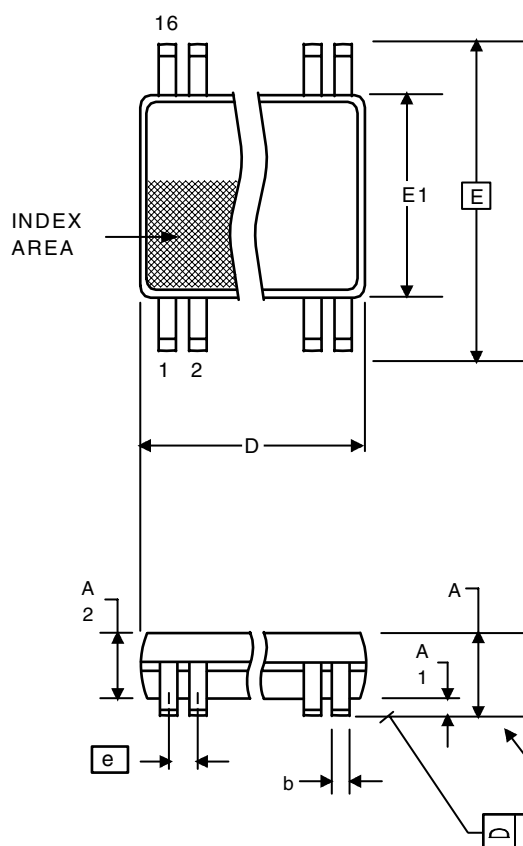


Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	1.35	1.75	.0532	.0688
A1	0.10	0.25	.0040	.0098
B	0.33	0.51	.013	.020
C	0.19	0.25	.0075	.0098
D	9.80	10.00	.3859	.3937
E	3.80	4.00	.1497	.1574
e	1.27 BASIC		0.050 BASIC	
H	5.80	6.20	.2284	.2440
h	0.25	0.50	.010	.020
L	0.40	1.27	.016	.050
α	0°	8°	0°	8°

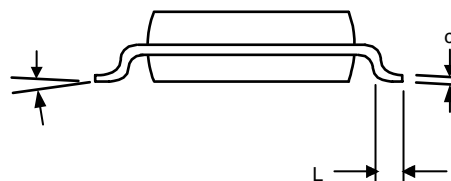


Package Outline and Package Dimensions (16-pin TSSOP, 4.40 mm Body, 0.65 mm Pitch)

Package dimensions are kept current with JEDEC Publication No. 95



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	--	1.20	--	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
b	0.19	0.30	0.007	0.012
C	0.09	0.20	0.0035	0.008
D	4.90	5.1	0.193	0.201
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	0.169	0.177
e	0.65 Basic		0.0256 Basic	
L	0.45	0.75	0.018	0.030
α	0°	8°	0°	8°
aaa	--	0.10	--	0.004



Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
2308B-1DC	Tubes	16-pin SOIC	0 to +70° C
2308B-1DCI	Tubes	16-pin SOIC	-40 to +85° C
2308B-1DCG	Tubes	16-pin SOIC	0 to +70° C
2308B-1DCGI	Tubes	16-pin SOIC	-40 to +85° C
2308B-1DC8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-1DCI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-1DCG8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-1DCGI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-1HDC	Tubes	16-pin SOIC	0 to +70° C
2308B-1HDCI	Tubes	16-pin SOIC	-40 to +85° C
2308B-1HDCG	Tubes	16-pin SOIC	0 to +70° C
2308B-1HDCGI	Tubes	16-pin SOIC	-40 to +85° C
2308B-1HDC8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-1HDCI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-1HDCG8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-1HDCGI8	Tape and Reel	16-pin SOIC	-40 to +85° C

Part / Order Number	Shipping Packaging	Package	Temperature
2308B-1HPG	Tubes	16-pin TSSOP	0 to +70° C
2308B-1HPGI	Tubes	16-pin TSSOP	-40 to +85° C
2308B-1HPGG	Tubes	16-pin TSSOP	0 to +70° C
2308B-1HPGGI	Tubes	16-pin TSSOP	-40 to +85° C
2308B-1HPG8	Tape and Reel	16-pin TSSOP	0 to +70° C
2308B-1HPGI8	Tape and Reel	16-pin TSSOP	-40 to +85° C
2308B-1HPGG8	Tape and Reel	16-pin TSSOP	0 to +70° C
2308B-1HPGGI8	Tape and Reel	16-pin TSSOP	-40 to +85° C
2308B-2DC	Tubes	16-pin SOIC	0 to +70° C
2308B-2DCI	Tubes	16-pin SOIC	-40 to +85° C
2308B-2DCG	Tubes	16-pin SOIC	0 to +70° C
2308B-2DCGI	Tubes	16-pin SOIC	-40 to +85° C
2308B-2DC8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-2DCI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-2DCG8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-2DCGI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-3DCG	Tubes	16-pin SOIC	0 to +70° C
2308B-3DCGI	Tubes	16-pin SOIC	-40 to +85° C
2308B-3DCG8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-3DCGI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-4DC	Tubes	16-pin SOIC	0 to +70° C
2308B-4DCI	Tubes	16-pin SOIC	-40 to +85° C
2308B-4DCG	Tubes	16-pin SOIC	0 to +70° C
2308B-4DCGI	Tubes	16-pin SOIC	-40 to +85° C
2308B-4DC8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-4DCI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-4DCG8	Tape and Reel	16-pin SOIC	0 to +70° C
2308B-4DCGI8	Tape and Reel	16-pin SOIC	-40 to +85° C
2308B-5HPG	Tubes	16-pin TSSOP	0 to +70° C
2308B-5HPGI	Tubes	16-pin TSSOP	-40 to +85° C
2308B-5HPGG	Tubes	16-pin TSSOP	0 to +70° C
2308B-5HPGGI	Tubes	16-pin TSSOP	-40 to +85° C
2308B-5HPG8	Tape and Reel	16-pin TSSOP	0 to +70° C
2308B-5HPGI8	Tape and Reel	16-pin TSSOP	-40 to +85° C
2308B-5HPGG8	Tape and Reel	16-pin TSSOP	0 to +70° C
2308B-5HPGGI8	Tape and Reel	16-pin TSSOP	-40 to +85° C

The IDT2308B-1, -2, -3, and -4 are Zero Delay Clock Buffers with Standard Drive.

The IDT2308B-1H, -2H, and -5H are Zero Delay Clock Buffers with High Drive.

Parts ordered with a "G" after the two-letter package code are the Pb-Free configuration and are RoHS compliant.

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Revision History

Rev.	Originator	Date	Description of Change
11/2008		11/2008	Initial release.
B	D. Larson	03/05/09	Updated part ordering to include 2308B-3DCG and -3DCGI.

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